# 826469-5 - ACTIVE

### AMPMODU | AMPMODU Headers

TE Internal #: 826469-5 PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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### Connectors > PCB Connectors > PCB Headers & Receptacles



## PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **10** 

Number of Rows: 2

### Features

### Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Partially Shrouded



Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	10
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



PCR Contact Termination Area Plating Material Thickness3 µmMating Pin DiameterA3 mm(.025 in]Contact Shape & FormRoundContact Underplating MaterialTinContact Termination Area Plating MaterialGoldContact Mating Area Plating MaterialGoldContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Hickness& Jun (2015 in)Contact Current Rating (Max)S AContact Current Rating (Max)& S AContact Current Rating (Max)& S ATermination Post & Tai Diameter& Min(.025 in)Termination Post & Tai Diameter& S mm(.025 in)Mating Retendion TypeDetent LatchingMating Retendion TypeWithMating Retendion TypeWithMating Alignment TypeWithoutConnector Mouning TypeWithoutConnector Mouning TypePCTConnector Mouning TypePCTConnector Mouning TypePCTConnector Mouning TypeS form(.1 in)Connector Mouning TypeS form(.1 in)Connector Mouning TypeS form(.1 in)Connector Mouning Type <th></th> <th></th>		
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PCB Contact Termination Area Plating MaterialTinContact Base MaterialPhosphor BronzeContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness& µm[31.5 µin]Contact TypePinContact Current Rating (Max)S AFermination Features	Contact Shape & Form	Round
Contact Base MaterialPhosphor BronzeContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness8 µm[31.5 µin]Contact TypePinContact Current Rating (Max)5 AFound Termination Post & Tail Diameter.63 mm[.025 in]Termination Post & Tail Diameter.63 mm[.025 in]Mating RetentionS zerminationMating Retention TypeDetent LatchingMating Retention TypeDetent LatchingMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount RetentionWithoutConnector Mounting TypeBoard MountPCB Mount Alignment.254 mm[.1 in]Posing Material.254 mm[.1 in]Po	Contact Underplating Material	Nickel
Contact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness8 µm[31.5 µin]Contact TypePinContact Current Rating (Max)5 AFermination Peatures63 nm[025 in]Termination Post & Tail Length32 nm[126 in]Termination Post & Tail Length32 nm[126 in]Termination Post & Tail Length32 nm[126 in]Mating RetentionWithMating RetentionWithMating Retention TypeDetent LatchingPCB Mount RetentionWithoutPCB Mount RetentionWithoutConnector Mounting TypeBoard MountPCB Mount AlignmentPCTHusing Material2.54 nm[1 in]Husing Material2.54 nm[1 in]PCB Nourt Alignment2.54 nm[1 in]PCB Mount RetentionPCTPCB Mount Retention2.54 nm[1 in]PCB Nourt RetentionPCTPCB Mount Retention2.54 nm[1 in]PCB Nourt RetentionPCTPCB Nourt AlignmentSch mount and sch materialPCB Nourt Retention2.54 nm[1 in]PCB Nourt Retention2.54 nm[1 in]PCB Nourt Alignment2.54 nm[1 in]PCB Nourt Alignment2.54 nm[1 in]PCB Nourt Alignment1.57 nm[0.62 in]PCB Nourt Alignment	PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Thickness& pm[31.5 pin]Contact TypePinContact TypeS AContact Current Rating (Max)S AFound Termination Post & Tail Diameter.43 mm[.025 in]Termination Post & Tail Length.32 mm[.126 in]Termination Method to Printed Circuit BoardThrough Hole - SolderMating RetentionWithMating Retention TypeDetent LatchingMating Retention TypeDetent LatchingMating AlignmentWithoutPCB Mount RetentionWithoutConnector Mounting TypeBaard MountFusing FeaturesConnector Mounting TypePolarization.24 mm[.1 in]Housing Material.57 mm[.062 in]Polarization.57 mm[.062 in]Polarization.57 mm[.062 in]Polarization.57 mm[.062 in]Polarizations.57 mm[.062 in]Pola	Contact Base Material	Phosphor Bronze
Contact TypePinContact Current Rating (Max)5 ATermination FeaturesRound Termination Post & Tail Diameter.63 mm[.025 in]Termination Post & Tail Length.32 mm[.126 in]Termination Method to Printed Circuit BoardThrough Hole-SolderMating RetentionWithMating Retention TypeDetent LatchingMating Retention TypePolarizationPCB Mount RetentionWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithoutConnector Mounting TypeBoard MountHousing Material.54 mm[.1 in]PCB Nourt Alignment.54 mm[.1 in]PCB Nourt Alignment.54 mm[.1 in]PCB Nourt Alignment.54 mm[.1 in]PCB Nourt Alignment.54 mm[.1 in]PCB Nourt Alignment.55 mm[.062 in]PCB Nourt Alignment.55 mm[.062 in]PCB Nourt Alignment.55 mm[.062 in]PCB Thickness (Recommended).57 mm[.062 in]PCB Thickness (Recommended).57 mm[.062 in]PCB Thickness (Recommended).57 mm[.062 in]PCB Thickness (Retention PCB	Contact Mating Area Plating Material	Gold
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Termination Pest & Tail Diameter       .63 mm[.025 in]         Termination Post & Tail Length       .32 mm[.025 in]         Termination Post & Tail Length       .32 mm[.126 in]         Termination Method to Printed Circuit Board       Through Hole - Solder         Wethanical Attachment         Mating Retention       With         Mating Retention Type       Detent Latching         Mating Alignment Type       Polarization         PCB Mount Retention       Without         PCB Mount Retention       Without         Connector Mounting Type       Board Mount         PCB Mount Alignment       Schamm[.1 in]         Housing Material       PCT         PCN       Schamm[.1 in]         Row-to-Row Spacing       Schamm[.1 in]         PCB Thickness (Recommended)       Schamm[.1 in]         PCN       Schamm[.1 in]         Material       PCT         PCN       Schamm[.1 in]         PCN	Contact Type	Pin
Round Termination Post & Tail Diameter	Contact Current Rating (Max)	5 A
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Nating Retention TypeDetent LatchingMating AlignmentWithMating Alignment TypePolarizationPCB Mount RetentionWithoutPCB Mount AlignmentWithoutConnector Mounting TypeBoard MountHousing FeaturesStarm[1 in]Centerline (Pitch)2.54 mm[1 in]Newsto-Row SpacingPCTRow-to-Row Spacing1.57 mm[.062 in]PCB Thickness (Recommended)1.57 mm[.062 in]Housing Temperature RatingHigh	Mechanical Attachment	
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Connector Mounting TypeBoard MountHousing Features2.54 mm[.1 in]Centerline (Pitch)2.54 mm[.1 in]Housing MaterialPCTNow-to-Row Spacing2.54 mm[.1 in]PCB Thickness (Recommended)1.57 mm[.062 in]Jaage ConditionsHuusing Temperature Rating	PCB Mount Retention	Without
Housing Features       2.54 mm[.1 in]         Centerline (Pitch)       2.54 mm[.1 in]         Housing Material       PCT         Dimensions       2.54 mm[.1 in]         Row-to-Row Spacing       2.54 mm[.1 in]         PCB Thickness (Recommended)       1.57 mm[.062 in]         Jaage Conditions       Housing Temperature Rating	PCB Mount Alignment	Without
Centerline (Pitch)2.54 mm[.1 in]Housing MaterialPCTImmensionsStamm[.1 in]Row-to-Row Spacing2.54 mm[.1 in]PCB Thickness (Recommended)1.57 mm[.062 in]Jsage ConditionsHousing Temperature Rating	Connector Mounting Type	Board Mount
Housing MaterialPCTImensions2.54 mm[.1 in]Row-to-Row Spacing2.54 mm[.062 in]PCB Thickness (Recommended)1.57 mm[.062 in]Jaage ConditionsHigh	Housing Features	
Dimensions         Row-to-Row Spacing       2.54 mm[.1 in]         PCB Thickness (Recommended)       1.57 mm[.062 in]         Jsage Conditions       Housing Temperature Rating	Centerline (Pitch)	2.54 mm[.1 in]
Row-to-Row Spacing2.54 mm[.1 in]PCB Thickness (Recommended)1.57 mm[.062 in]Jsage ConditionsHousing Temperature Rating	Housing Material	PCT
PCB Thickness (Recommended) 1.57 mm[.062 in]   Usage Conditions Housing Temperature Rating	Dimensions	
Jsage Conditions         Housing Temperature Rating         High	Row-to-Row Spacing	2.54 mm[.1 in]
Housing Temperature Rating High	PCB Thickness (Recommended)	1.57 mm[.062 in]
	Usage Conditions	
Operating Temperature Range -65 – 105 °C[-85 – 221 °F]	Housing Temperature Rating	High
	Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
		00/00/2022

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PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, CUL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	200
Packaging Type	Box
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE

2023 (235)

Does not contain REACH SVHC

Not Low Halogen - contains Br or Cl > 900 ppm.

Pin-in-Paste capable to 260°C

### Halogen Content

Solder Process Capability

### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**

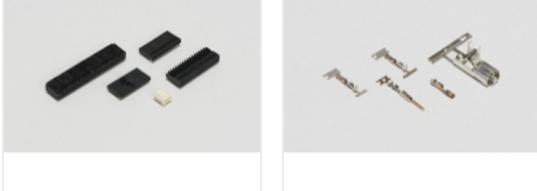
PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





# Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Conr
& Housings(5)	

#### Wire-to-Board Connector Contacts(65)

# Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





## Documents

### Product Drawings 2X5P MOD II SHROUDED HEADER, ST

English

### **CAD** Files

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_826469-5\_E.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_826469-5\_E.3d\_igs.zip

English

Customer View Model

### ENG\_CVM\_CVM\_826469-5\_E.3d\_stp.zip

English

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Product Environmental Compliance MD\_826469-5\_05192016167\_dmtec

English

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English

Agency Approvals

UL Report

English